



### **General Description**

The WSF20N20 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSF20N20 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

### **Product Summery**

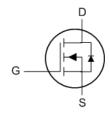
BVDSS	RDSON	ID
200V	136mΩ	20A

# **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch

# **TO-252 Pin Configuration**





# **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	200	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	20	Α
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	12	Α
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	6	Α
I <sub>D</sub> @T <sub>A</sub> =70℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	4.5	Α
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	64	Α
EAS	Single Pulse Avalanche Energy <sup>3</sup>	35	mJ
l <sub>AS</sub>	Avalanche Current	5	Α
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation <sup>3</sup>	50	W
P <sub>D</sub> @T <sub>c</sub> =100℃	Total Power Dissipation <sup>3</sup>	20	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	$^{\circ}$
$T_J$	Operating Junction Temperature Range -55 to 150		$^{\circ}$ C

### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>0JA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>		50	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		2.5	°C/W



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	200			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25 $^{\circ}\mathrm{C}$ , I <sub>D</sub> =1mA		0.098		V/°C
D	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =8A		136	160	mΩ
$R_{DS(ON)}$		V <sub>GS</sub> =6.0V , I <sub>D</sub> =4A		200	380	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	\/ -\/   -250\	1.0	2.0	3.0	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-4.57		mV/℃
	Drain Source Lookage Current	V <sub>DS</sub> =160V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =160V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 25V$ , $V_{DS}$ = $0V$			±100	nA
gfs	Forward Transconductance	$V_{DS}$ =5 $V$ , $I_{D}$ =8 $A$		20		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2	4	Ω
$Q_g$	Total Gate Charge (10V)	V <sub>DS</sub> =100V , V <sub>GS</sub> =10V , I <sub>D</sub> =8A		68		
$Q_{gs}$	Gate-Source Charge			42		nC
$Q_{gd}$	Gate-Drain Charge			35		
T <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD}$ =30V , $V_{GS}$ =10V , $R_{G}$ =6 $\Omega$ $I_{D}$ =10A RL=30 $\Omega$		17		
Tr	Rise Time			11		
T <sub>d(off)</sub>	Turn-Off Delay Time			47		ns
T <sub>f</sub>	Fall Time			14		
Ciss	Input Capacitance	V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , f=1MHz		3100		
C <sub>oss</sub>	Output Capacitance			210		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			150		

### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.1mH , I <sub>AS</sub> =5A	20			mJ

# **Diode Characteristics**

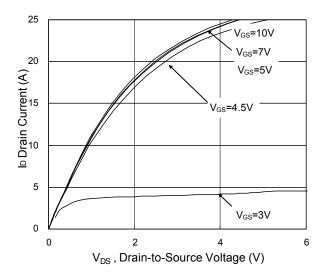
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	V =V =0V Force Current			20	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			64	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =5A , T <sub>J</sub> =25℃			1.1	V
t <sub>rr</sub>	Reverse Recovery Time			105		nS
Q <sub>rr</sub>	Reverse Recovery Charge	IF=5A , dI/dt=100A/ $\mu$ s , T $_{J}$ =25 $^{\circ}$ C		360		nC

#### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, t<10 sec.
- 2.The data tested by pulsed , pulse width  $\,\leq\,300\text{us}$  , duty cycle  $\,\leq\,2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}\text{=}25\text{V}, V_{\text{GS}}\text{=}10\text{V}, L\text{=}0.1\text{mH}, I_{\text{AS}}\text{=}5\text{A}$
- 5.The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.



# **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

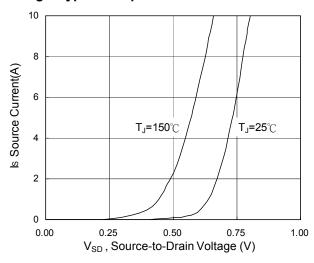


Fig.3 Forward Characteristics Of Reverse

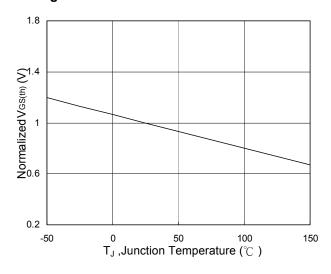


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

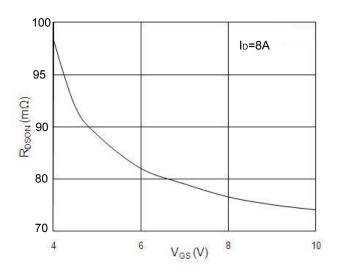


Fig.2 On-Resistance vs. Gate-Source

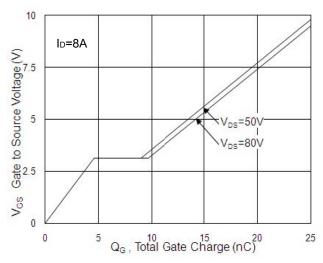


Fig.4 Gate-Charge Characteristics

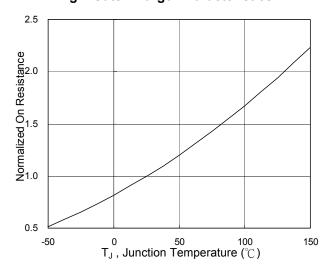
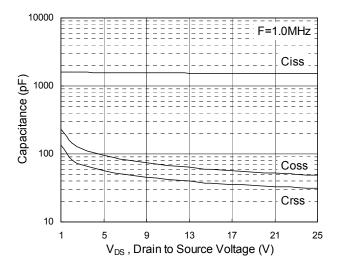


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>







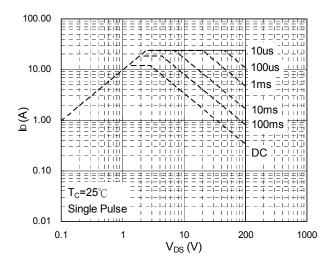


Fig.7 Capacitance

Fig.8 Safe Operating Area

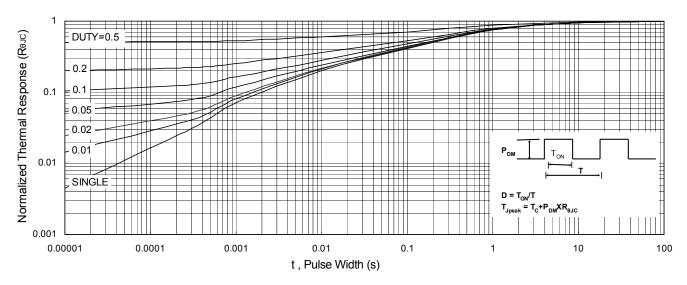


Fig.9 Normalized Maximum Transient Thermal Impedance

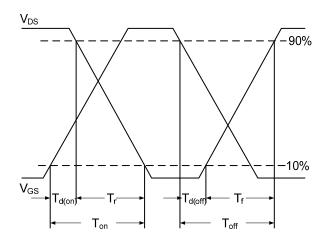


Fig.10 Switching Time Waveform

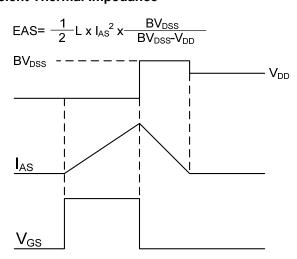


Fig.11 Unclamped Inductive Switching Waveform



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